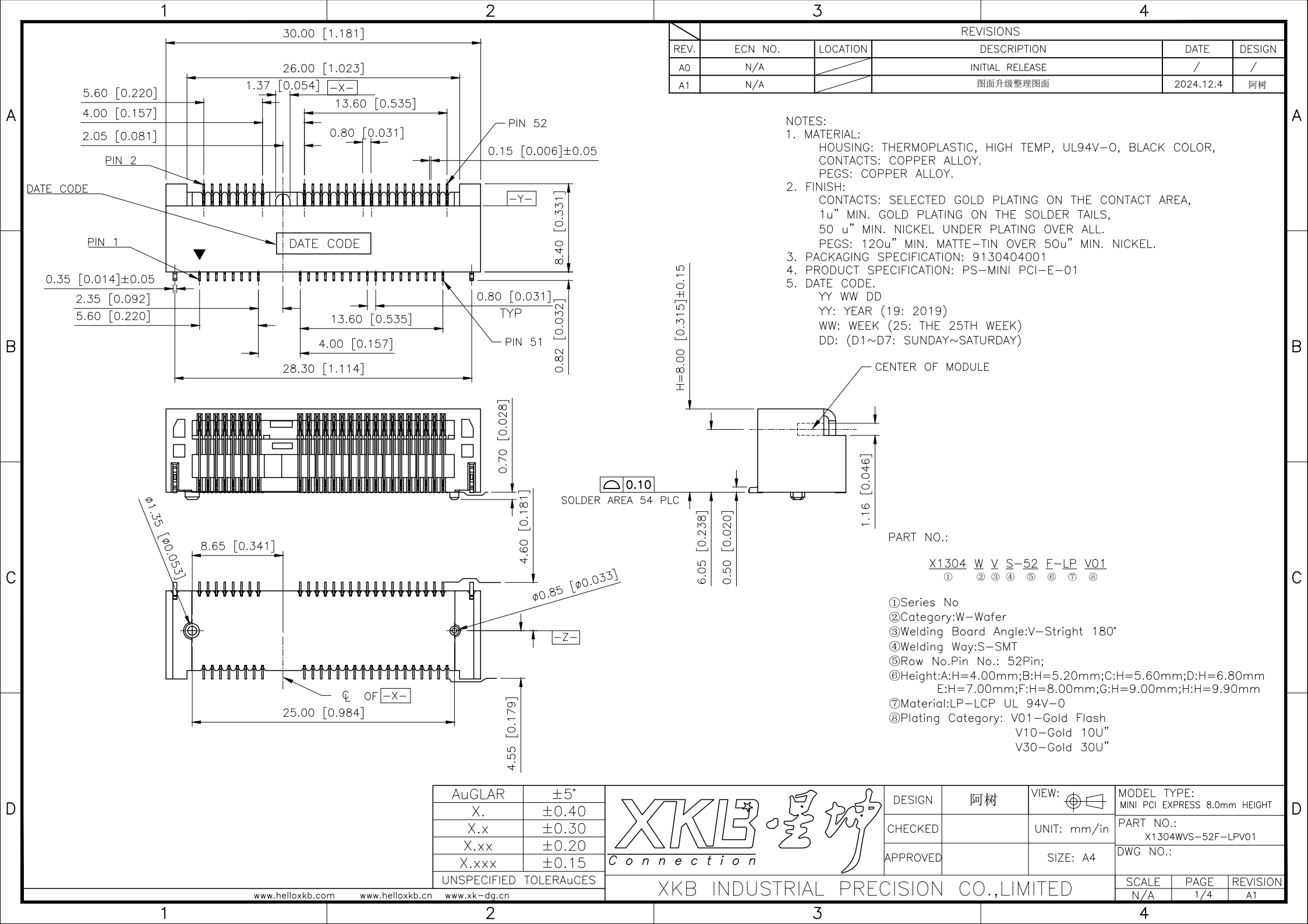




REVISIONS					
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A0	N/A		INITIAL RELEASE	/	/
A1	N/A		图面升级整理图面	2024.12.4	阿树

- NOTES:
- MATERIAL:
HOUSING: THERMOPLASTIC, HIGH TEMP, UL94V-O, BLACK COLOR,
CONTACTS: COPPER ALLOY.
PEGS: COPPER ALLOY.
 - FINISH:
CONTACTS: SELECTED GOLD PLATING ON THE CONTACT AREA,
1u" MIN. GOLD PLATING ON THE SOLDER TAILS,
50 u" MIN. NICKEL UNDER PLATING OVER ALL.
PEGS: 120u" MIN. MATTE-TIN OVER 50u" MIN. NICKEL.
 - PACKAGING SPECIFICATION: 9130404001
 - PRODUCT SPECIFICATION: PS-MINI PCI-E-01
 - DATE CODE.
YY WW DD
YY: YEAR (19: 2019)
WW: WEEK (25: THE 25TH WEEK)
DD: (D1~D7: SUNDAY~SATURDAY)

PART NO.:

X1304 W V S-52 F-LP V01
① ② ③ ④ ⑤ ⑥ ⑦ ⑧

- ①Series No
②Category:W-Wafer
③Welding Board Angle:V-Stright 180°
④Welding Way:S-SMT
⑤Row No.Pin No.: 52Pin;
⑥Height:A:H=4.00mm;B:H=5.20mm;C:H=5.60mm;D:H=6.80mm
E:H=7.00mm;F:H=8.00mm;G:H=9.00mm;H:H=9.90mm
⑦Material:LP-LCP UL 94V-0
⑧Plating Category: V01-Gold Flash
V10-Gold 10U"
V30-Gold 30U"

AuGLAR	±5°
X.	±0.40
X.x	±0.30
X.xx	±0.20
X.xxx	±0.15
UNSPECIFIED TOLERANCES	



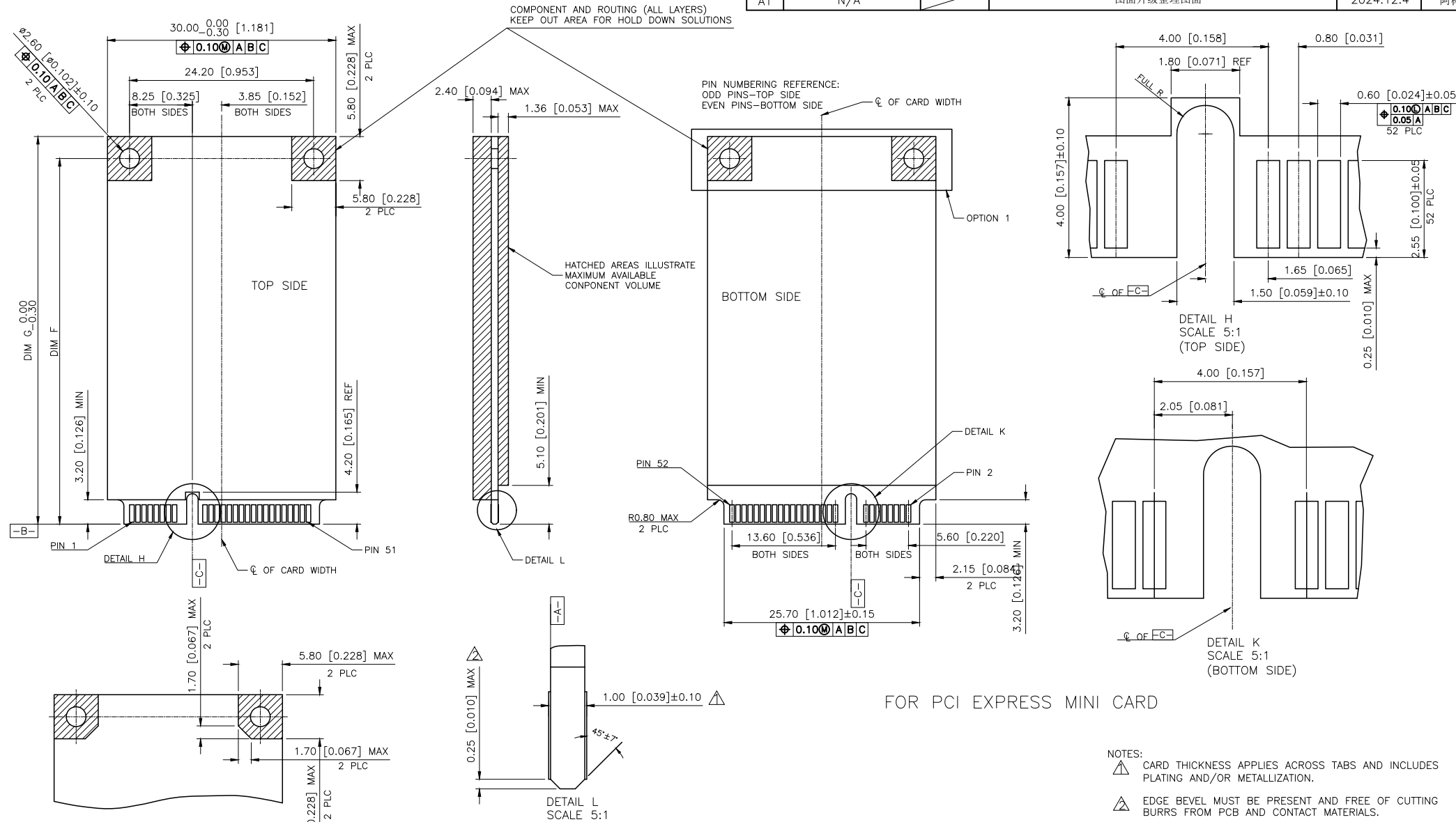
DESIGN	阿树	VIEW:	MINI PCI EXPRESS 8.0mm HEIGHT
CHECKED		UNIT:	mm/in
APPROVED		SIZE:	A4

XKB INDUSTRIAL PRECISION CO.,LIMITED

SCALE	PAGE	REVISION
N/A	1/4	A1

DIM F	DIM G	
48.05	50.95	FULL-MINI CARD
23.90	26.80	HALF-MINI CARD

REVISIONS					
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A0	N/A		INITIAL RELEASE	/	/
A1	N/A		图面升级整理图面	2024.12.4	阿树



AuGLAR	±5°
X.	±0.40
X.x	±0.30
X.xx	±0.20
X.xxx	±0.15
UNSPECIFIED TOLERANCES	



DESIGN	阿树	VIEW:	MODEL TYPE: MINI PCI EXPRESS 8.0mm HEIGHT
CHECKED		UNIT: mm/in	PART NO.: X1304WVS-52F-LPV01
APPROVED		SIZE: A4	DWG NO.:

DIM F	DIM G	
48.05	50.95	FULL CARD
23.90	26.80	HALF CARD

REVISIONS				
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE
A0	N/A		INITIAL RELEASE	/
A1	N/A		图面升级整理图面	2024.12.4

